Abstract

A heat resistant positive-working photosensitive PBO precursor composition comprising:

(a) at least one polybenzoxazole precursor polymer;

(a) at least one plasticizer compound;

(b) at least one solvent;

wherein the amount of the plasticizer present in the composition is an amount effective to reduce the sidewall angle of imaged and cured features in the coated film on the substrate to prevent stress failures in subsequent metallization of the substrate due to steep angles of the imaged features, and with the proviso that if the polybenzoxazole precursor polymer solely consists of polybenzoxazole precursor polymers that do not contain a photoactive moiety on the polymer, then (c) at least one photoactive compound is also present in the composition.